

SSC8160GS6

N-Channel Small Switching MOSFET with ESD Protection

> Features

VDS	VGS	RDSON Typ.	ID	ESD
60V	±20V	2R@10V	0.24	3kV
		3R@4V5	0.3A	

> Description

This device is an N-Channel enhancement mode MOSFET, with low on-resistance, fast switching speed and low threshold voltage, it is ideal for portable equipment.

Applications

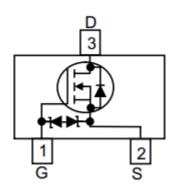
- Direct Logic-Level Interface: TTL/CMOS
- Drivers: Relays, Solenoids,Lamps, Hammers
- Display, Memories, Transistors, etc.
- Battery Operated System
- Solid-State Relays

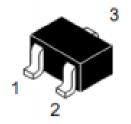
> Ordering Information

Device	Package	Shipping		
SSC8160GS6	SOT23	3000/Reel		

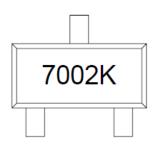
Pin configuration

Top view





SOT23



Marking



➤ **Absolute Maximum Ratings**(T_A=25°C unless otherwise noted)

Symbol	Parameter	Ratings	Unit	
V_{DSS}	Drain-to-Source Voltage	60	V	
V _{GSS}	Gate-to-Source Voltage	±20	V	
l _D	Continuous Drain Current ^a	0.3	Α	
I _{DM}	Pulsed Drain Current ^b	0.8	Α	
P _D	Power Dissipation ^c	0.83	W	
P _{DSM}	Power Dissipation ^a	0.35	W	
TJ	Operation junction temperature	-55 to 150	°C	
Тѕтс	Storage temperature range	-55 to 150	°C	

➤ Thermal Resistance Ratings($T_A=25^{\circ}$ C unless otherwise noted)

Symbol	Parameter	Typical	Maximum	Unit
$R_{\theta JA}$	Junction-to-Ambient Thermal Resistance ^a		357	°C/W
$R_{ heta JC}$	Junction-to-Case Thermal Resistance		159	C/VV

Note:

- a. The value of $R_{\theta JA}$ is measured with the device mounted on 1 in² FR-4 board with 2oz.copper,in a still air environment with T_A =25 C° . The value in any given application depends on the user is specific board design. The current rating is based on the t \leq 10s thermal resistance rating.
- b. Repetitive rating, pulse width limited by junction temperature.
- c. The power dissipation P_D is based on $T_{J(MAX)}$ =150°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.

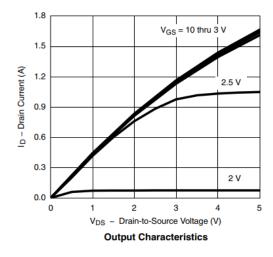


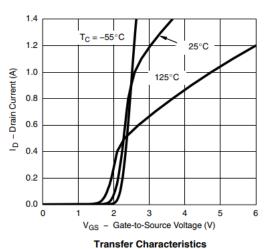
➤ **Electronics Characteristics**(T_A=25°C unless otherwise noted)

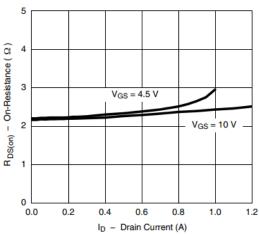
Symbol	Parameter	Test Conditions	Min	Тур.	Max	Unit
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	VGS=0V,ID=10uA	60			V
$V_{\text{GS }(\text{th})}$	Gate Threshold Voltage	VDS=VGS,ID=250uA	1		2.5	V
Б	Drain-Source On-	VGS=10V,ID=0.5A		2	6.6	R
$R_{DS(on)}$	Resistance	VGS=4.5V,ID=0.05A		3	8	
I _{DSS}	Zero Gate Voltage Drain Current	VDS=60V,VGS=0V			1	uA
I _{GSS}	Gate-Source leak	VGS=±20V,VDS=0V			±10	uA
G_{FS}	Transconductance	VDS=10V,ID=0.2A		80		mS
V _{SD}	Forward Voltage	VGS=0V,IS=0.2A		0.7	1.3	V
Ciss	Input Capacitance	VDS=25V, VGS=0V, f=1MHz		32		
Coss	Output Capacitance			7		pF
Crss	Reverse Transfer Capacitance			3		
$T_{D(ON)}$	Turn-on delay time	V00 404		4.2		
Tr	Rise Time	VGS=10V, VDS=20V, RG=20R, RL=60R		3.8		ns
$T_{D(OFF)}$	Turn-off delay time			22		
Tf	Fall Time			14		
Q _G	Total Gate Charge	VGS=10V, VDS=15V, ID=0.2A		0.4		
Qgs	Gate Source Charge			0.1		nC
Q_{GD}	Gate Drain Charge			0.11		

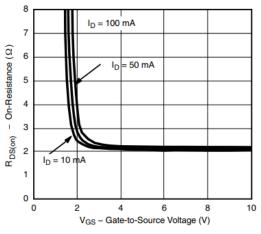


➤ Typical Characteristics(T_A=25°C unless otherwise noted)

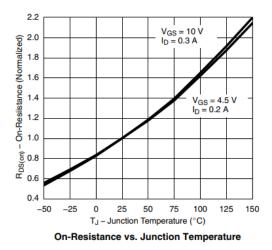


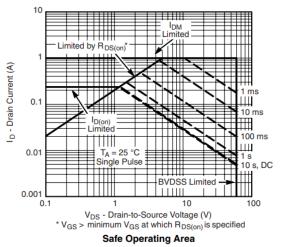






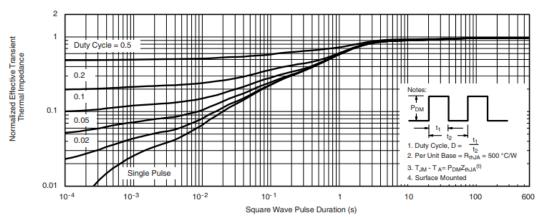
On-Resistance vs. Drain Current On-Resistance vs. Gate-to-Source Voltage





www.sscsemi.com Rev.2.0

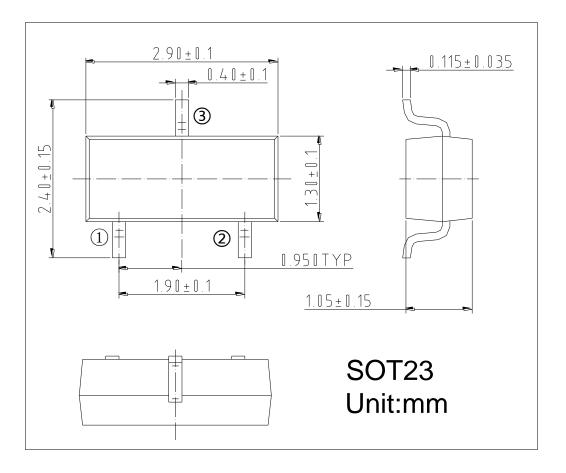




Normalized Thermal Transient Impedance, Junction-to-Ambient



Package Information



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